Amendments to the Claims:

This listing of claims replaces all prior versions and listings of claims in the application:

Listing of Claims:

1. (Currently amended) A process for preparing a porous wiring interlayer insulating film having very low dielectric constant for a semiconductor comprising the steps of:

a) preparing a mixed complex of matrix resin and pore-forming ~~organic molecules~~ material, the matrix resin is selected from the group consisting essentially of:

organosilane of Chemical Formula 1: $R^1_mR^2_nSiX_{4-m-n}$ (where each of R^1 and R^2 which may be the same or different, is a non-hydrolysable group selected from hydrogen, alkyl, fluorine-containing alkyl or aryl group; X is a hydrolysable group selected from halide, alkoxy or acyloxy; and m and n are integers of from 0 to 3 satisfying $0 \leq m+n \leq 3$) or a partially hydrolyzed condensate thereof;

organic bridged silane of Chemical Formula 2: $R^3_pY_{3-p}Si\text{-}M\text{-}SiR^4_qZ_{3-q}$ (where each of R^3 and R^4 which may be the same or different, is a non-hydrolysable group selected from hydrogen, alkyl, fluorine-containing alkyl, alkenyl or aryl; each of Y and Z which may be the same or different, is a hydrolysable group selected from halide, alkoxy or acyloxy; M is alkylene or arylene group; and p and q are integers of from 0 to 2) or a cyclic oligomer with organic bridge unit (Si-M-Si) or a partially hydrolyzed condensate thereof; and

a mixture thereof; and

the pore-forming material containing an organic part having one or more thermally decomposable organic linkage groups, and at least one silyl functional group at the terminal of the pore-forming material so that the pore-forming material can be connected by covalent bonding with the matrix resin;

b) coating the mixed complex on a substrate; and

c) heating the mixed complex to remove the organic ~~molecules~~ part of the pore-forming material, thereby forming pores inside the complex.

2. (Canceled)

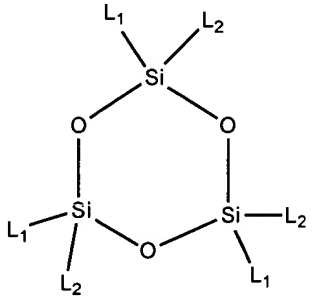
3. (Currently amended) The process according to claim[[2]] 1, wherein in the Chemical Formula 1, R^1 and R^2 are independently hydrogen, alkyl or phenyl and X is an alkoxy group.

4. (Currently amended) The process according to claim [[2]] 1, wherein the organosilane is selected from the group consisting of tetraalkoxysilane, monoalkyltrialkoxysilane, dialkyldialkoxysilane, ~~trialkylmonoalkoxysilane~~ trialkylmonoalkoxysilane, trialkoxysilane, monoalkyldialkoxysilane, and a mixture thereof.

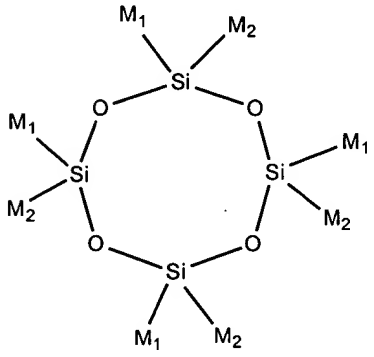
5. (Currently amended) The process according to claim [[2]] 1, wherein the organic bridged silane is synthesized by hydrosilylation reaction between a silane precursor containing a Si-H with a silane monomer containing aliphatic unsaturated carbon (-CH=CH_2-) in the presence of a catalyst.

6. (Currently amended) The process according to claim [[2]] 1, wherein the cyclic oligomer with organic bridged unit is synthesized by Grignard reaction of alkylhalide containing silane precursor.

7. (Currently amended). The process according to claim [[2]] 1, wherein the cyclic oligomer with organic bridge unit (Si-M-Si) is synthesized by [[the]] hydrosilylation reaction of a silane precursor containing a Si-H with an oligomer of ring structure (I) and/or (II):



(I)



(II)

wherein L_1 is alkenyl, L_2 is hydrogen, alkyl or aryl, M_1 is alkenyl, and M_2 is hydrogen, alkyl or aryl.

8. (Canceled)

9. (Currently amended) The process according to claim [[8]] 1, wherein the organic part of the pore-forming material contains organic linkage groups that can be decomposed at 200 to 500°C.

10. (Currently amended) The process according to claim 1, wherein the step a) comprises

partially hydrolyzing and condensing the matrix resin in an organic solvent after ~~the addition of~~ adding water and catalyst; and adding the pore-forming material to partially hydrolyzed condensate of the matrix resin; or

partially hydrolyzing and condensing the mixture of the matrix resin and pore-forming material in an organic solvent after ~~the addition of~~ adding water and catalyst.

11. (Original) The process according to claim 10, wherein the molecular weight of the partially hydrolyzed condensate product of the matrix resin or a mixture of the matrix resin and the pore-forming material is 500 to 1,000,000 as a weight average molecular weight.

12. (Canceled)

13. (Canceled)

14. (Original) The process according to claim 1, wherein the step c) comprises:

heating the mixed complex to 150 to 350°C to effect curing without significant thermolysis; and

further heating the cured complex to 350 to 600°C to effect thermolysis of the organic molecule part of the pore-forming material.

15. (Currently amended) The process according to claim 1, wherein the step c) comprises heating the mixed complex to 350°C up to the lesser of decomposition temperature of the matrix resin to simultaneously effect [[the]] curing of the complex and thermolysis of the organic molecule part of the pore-forming material.

16. (New) The process according to claim 1, wherein the thermally decomposable organic linkage groups are selected from ether group, ester group, amide group,

carbonate group, carbamate group, anhydride group, amine group, enamine group containing, imine, azo group, thio-ether group, sulfone, sulfoxide group, isocyanate group, isocyanurate group, triazine group, acid group, and epoxy group.